

Fiber optic displacement sensor based on micro-thickness measurement using bundled fiber and concave mirror

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In this paper, we propose and demonstrate a simple yet accurate optical fiber based sensor capable of performing micron and sub-micron thickness measurement. The proposed sensor is based on reflective displacement sensor, which consists of a 785 nm light source, multimode plastic bundle fiber probe, a concave mirror target and a silicon detector. A mechanical chopper is used in conjunction with lock in amplifier to allow sensitive detection free from ambient light interference. The thickness of the sample can be obtained from a linear equation correlating the thickness of the sample to the displacement of the sensor at which the peak output voltage is obtained, or by correlating the thickness of the sample directly to the peak output voltage measured. The sensitivity of the sensor is obtained at 1.0188mV/mm in the range of 0-0.64 mm of cover slips thickness.

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1. Introduction

Over the last few decades, measurement of thickness has become increasingly important in numerous research and development fields. For instance, measurement of the thickness of transparent plate, which typically ranges from several hundred microns to millimeters. This plate is used in applications such as liquid crystal display and optical windows. Many methods can be adopted for measuring the thickness parameter, whereas optical techniques are the most preferred as they are non-contact and more sensitive. Optical methods are typically based on interferometry techniques, which are sensitive to optical path difference. More advanced methods such as low coherence interferometry and wavelength-scanning interferometry with confocal microscopy [1-3] are normally used to determine the refractive index of the sample, which is then used to provide a highly accurate measurement of the thickness of the sample. The main drawbacks of these methods are they require critical optical alignment and high resolution translation stages [4].

Recently, fiber optic displacement sensors have gained a tremendous interest for various applications [5-8]. In this paper, a simple yet accurate non-contact thickness measurement system using a simple reflective fiber optic displacement sensor is proposed and demonstrated.

The proposed sensor utilizes a multimode plastic bundle fiber as a probe and a concave mirror as a target to perform accurate measurements in the micron and sub-micron range for thick film measurement.

2. Experimental setup

The experimental setup of the proposed micro-thickness measurement based on the reflective fiber optic displacement sensor is given in Fig. 1. The setup consists of a laser diode operating at 785 nm as a signal source and a 2 meter long bundled fiber, which consists of 16 multimode plastic fibre strands surrounding a central core. The central core of the probe acts as the transmitting fibre, which is connected to the signal source, while 16 cores surrounding the transmitting core acts as a receiving fiber, which is connected to a silicon photodiode (818 SL from Newport). The core size of the transmitting and the receiving fibres are approximately 1 mm and 0.25 mm, respectively in diameter. The laser output is modulated at a frequency of 113 Hz using a rotating mechanical chopper. This is to allow light detection using a lock-in amplifier (Model SR-510, Stanford Research Systems) that is connected to the silicon photodiode as to allow sensitive detection free from ambient light interference. The frequency is chosen so as to avoid the harmonics of the line frequency, which is approximately 50 to 60 Hz.

slips. In these curves, there are three maximum output voltage that can be used to determine the thickness of cover slips. In correlating the data obtained from the sensor to the thickness of the sample, the peak voltage approach is considered. This gives a linear equation on which the thickness of unknown samples can be determined. Fig. 4 shows the peak output voltage against the thickness of the samples. As shown in the figure, the relation is linear with the steepest slope of -1.0188 and a linear correlation coefficient of 0.98.

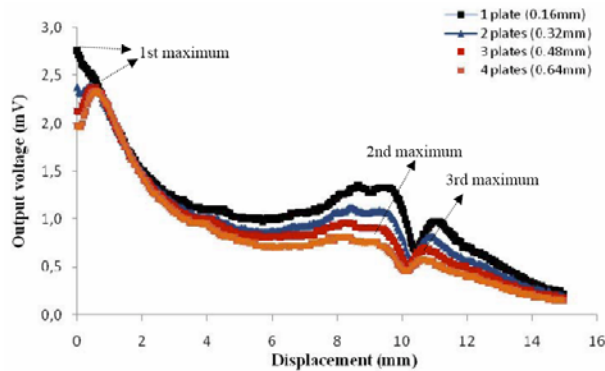


Fig. 3. Profile of the fiber optic displacement sensor for thickness measurement for 1-4 transparent plates.

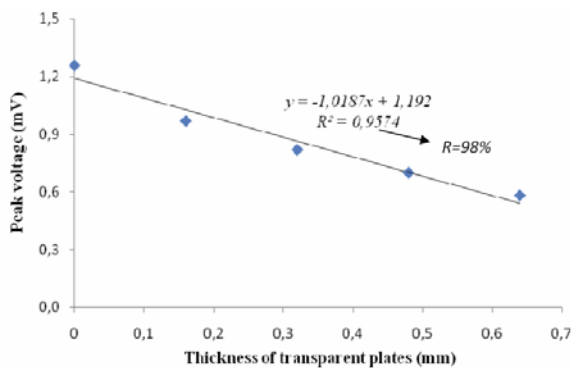


Fig. 4. Peak voltage at the third maximum as function of thickness of the transparent plates.

This method can be further expanded to include measurements of thick films in the region of 10 to 25 μm that are the layers in the fabrication of waveguide devices. Currently, thickness measurements for these thick films are performed using a prism coupler based on the contact technique, and at times can damage the surface of the film. This, in addition to the cost of the prism coupler technique makes the proposed setup a simple and attractive technique.

4. Conclusions

A simple and accurate optical fiber sensor capable of performing micron and sub-micron thickness measurement is proposed and demonstrated. The proposed sensor is based on reflective displacement sensor, which consists of a multimode plastic bundle fiber probe and a concave mirror. The thickness of the sample is computed using a linear equation derived from the correlation of the thickness of the sample directly to the peak output voltage measured at the third maximum. The sensitivity of the sensor is obtained at 1.0188mV/mm in the range of 0-0.64 mm of cover slips thickness. This method can be applied to measure thick films in the region of 10 to 25 μm that are the layers in the fabrication of waveguide devices.

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